

PCB DK and DF Extraction based on the Wheeler Incremental Inductance Method

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Abstract: DK and DF of the substrate have an important effect on the impedance matching of RF circuits, and they may change under the influence of high temperature during the PCB fabrication. Therefore, the DK DF extraction method for a fabrication finished PCB not a raw dielectric substrate is very important. Based on a pair of striplines, the proposed algorithm can extract the DK and DF values of a fabrication finished PCB substrate. It is named as an **on-stripline** extraction method. The proposed method is based on the derived differential mode and common mode attenuation constants of the stripline. The ration of them can eliminate the conductor roughness effect. The Djordjevic Dielectric model is used to represent a dispersive substrate in a broad frequency band. The advantages of the proposed method are: on-stripline, broadband, dispersive and eliminating the effect of the conductor roughness.

Introduction

- Accurate DK DF knowledge can avoid signal integrity and power integrity problems.

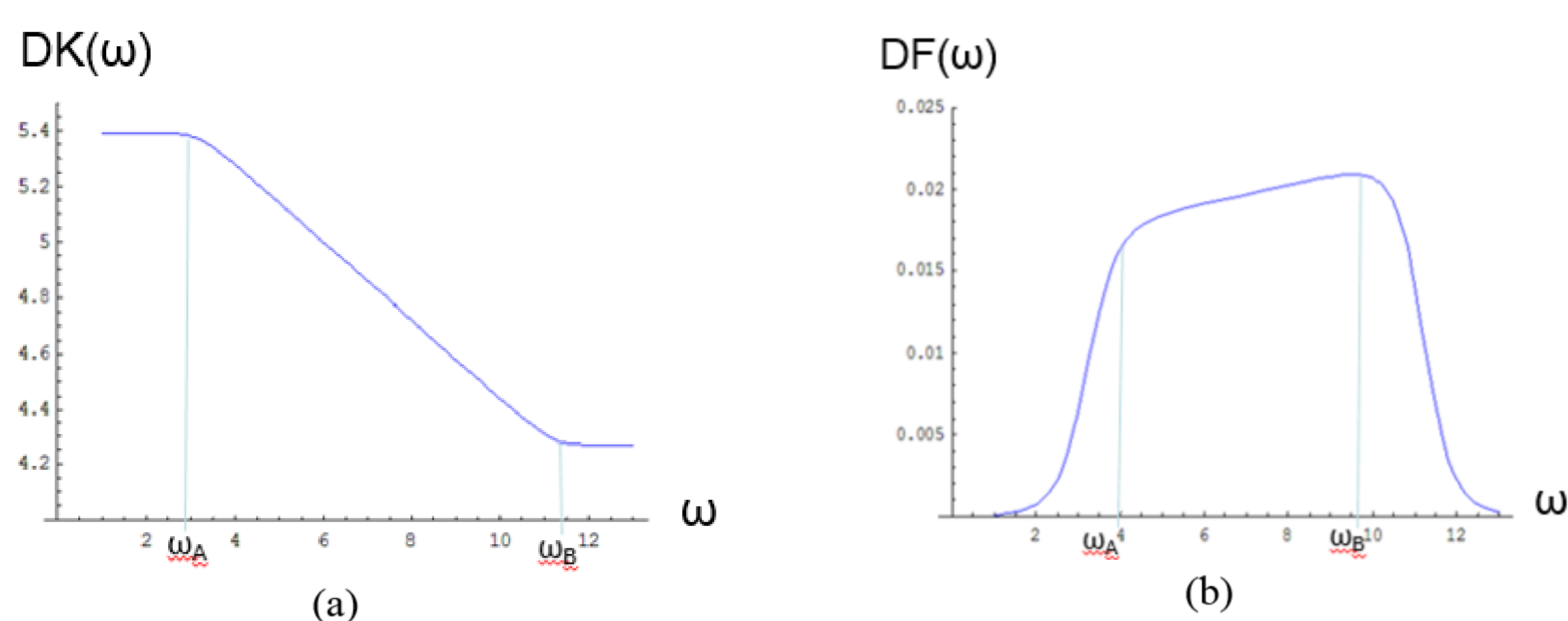


Fig. 1. (a) DK and (b) DF change with frequency changing.

- Many substrates are dispersive.

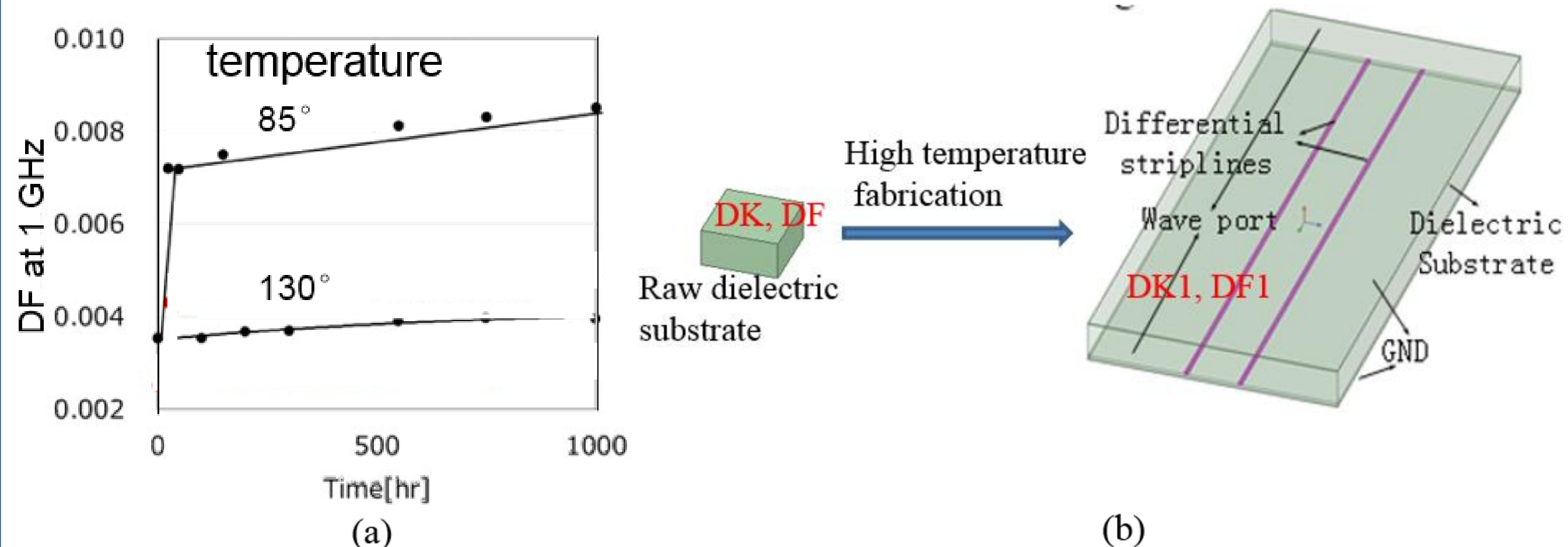


Fig. 2. (a) DF change with temperature changing, (b) DK, DF of raw substrate may be different from those of PCB substrate during high temperature fabrication.

- DK and DF of PCB substrate are different from those of raw dielectric substrate after PCB high temperature fabrication.

Proposed method details

$$\alpha_{dd,cc} = \alpha_{dd,cc}^{dielectric} + \alpha_{dd,cc}^{conductor} \quad (1)$$

- For attenuation constant from lossy dielectric substrates:

$$\alpha_{dd,cc}^{dielectric} = \text{real}(\gamma_{dd,cc}^{dielectric}) = \text{real}(j\omega\sqrt{\mu_0\epsilon}) = \sqrt{-\omega^2\mu_0\epsilon_0 DK(\omega)(1-jDF(\omega))} \quad (2)$$

- For attenuation constant from conductor striplines:

Wheeler Incremental Inductance method:

Lossy conductor contributes an ΔL :

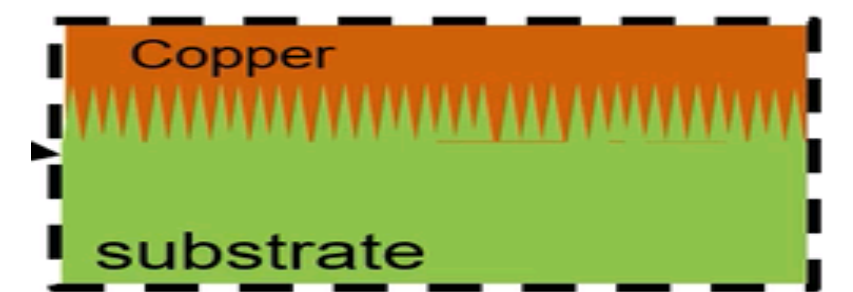
$$P_l = \int |\vec{H}_t|^2 dl / 2\sigma\delta_s = |I|^2 \omega\Delta L / 2, \quad P_{total} = |\vec{I}|^2 Z_0 / 2 \quad (3)$$

$$\alpha_{dd,cc}^{conductor} = P_l / 2P_{total} = \omega\Delta L_{dd,cc} / 2Z_{0dd,cc} \quad (4)$$

$$\alpha_{dd}(\omega) = HF \cdot \alpha_{dd,cc}^{conductor} + \alpha_{dd,cc}^{dielectric} = HF \cdot \omega\Delta L_{dd} / 2Z_{0dd} + \omega\sqrt{\mu_0\epsilon_0 DK(\omega)DF(\omega)} / 2$$

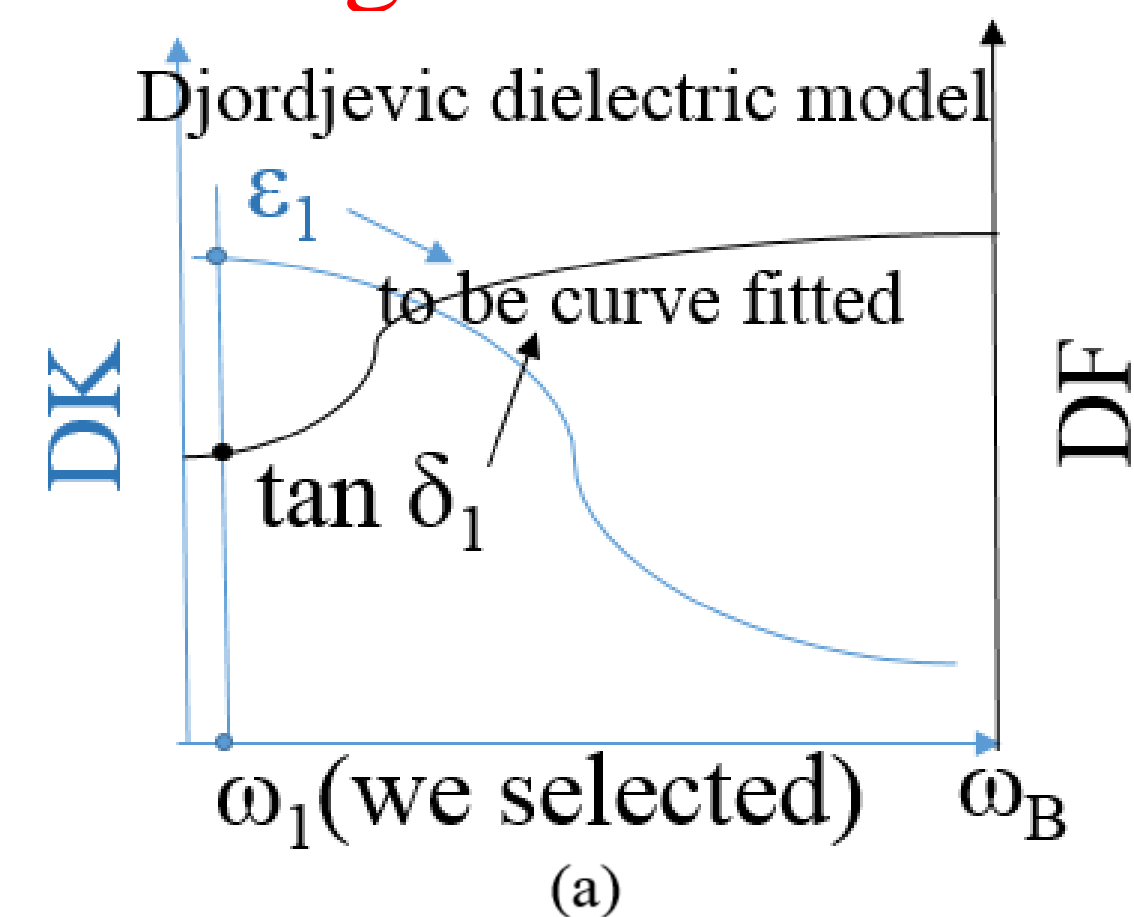
$$\alpha_{cc}(\omega) = HF \cdot \alpha_{dd,cc}^{conductor} + \alpha_{dd,cc}^{dielectric} = HF \cdot \omega\Delta L_{cc} / 2Z_{0cc} + \omega\sqrt{\mu_0\epsilon_0 DK(\omega)DF(\omega)} / 2 \quad (5)$$

Huray factor (HF):
conductor roughness



Novelty point

- $A(\omega)$ can **eliminate the influence of the conductor roughness.**



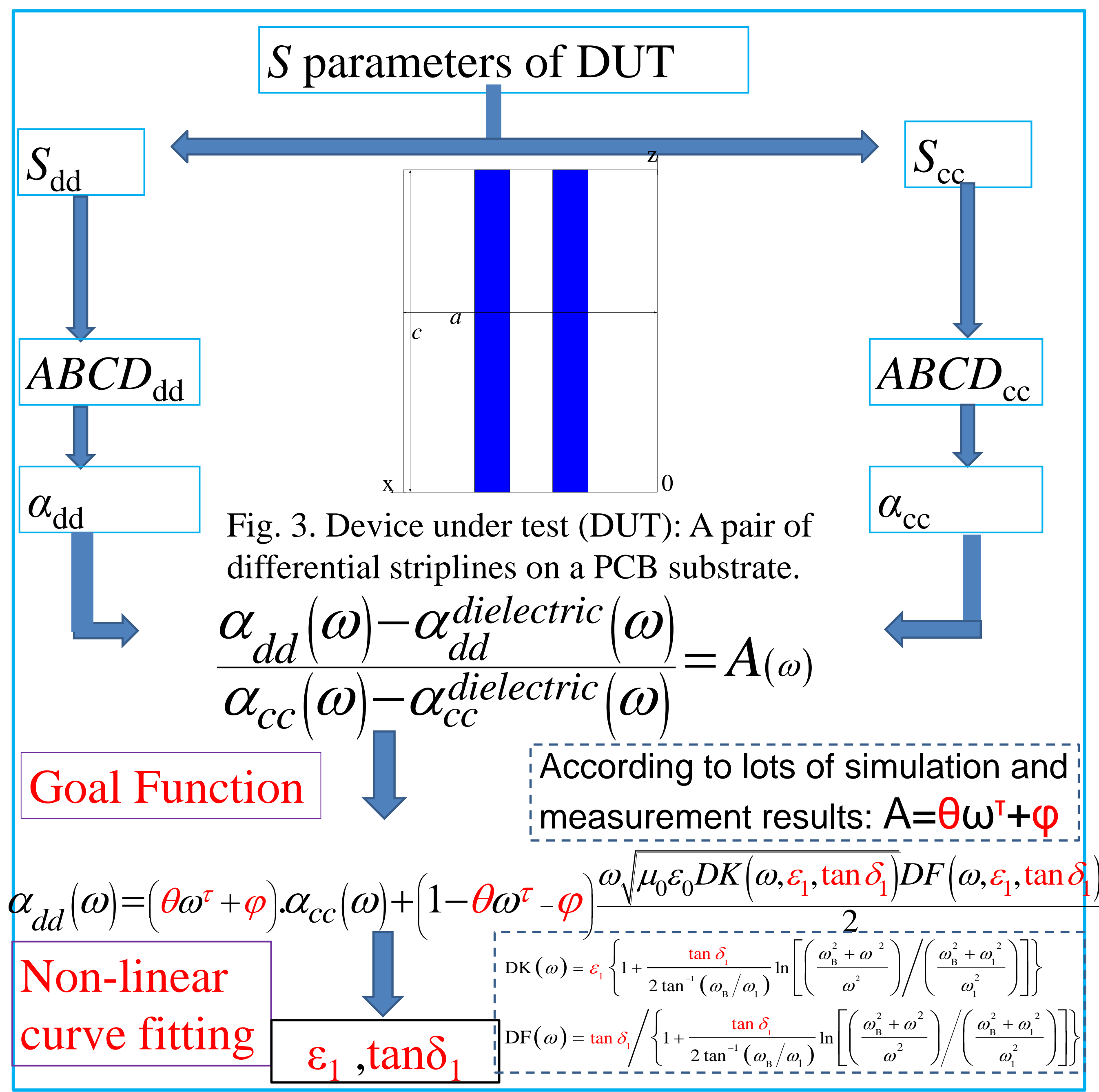
- Djordjevic Dielectric model use ϵ_1 , $\tan\delta_1$ to represent DK, DF function of a **dispersive** substrate in a **broad frequency band** with **only one measurement.**

- In goal function, α_{dd} and α_{cc} are obtained, θ , τ , ϕ , ϵ_1 , $\tan\delta_1$ are unknown to be curve fitted.

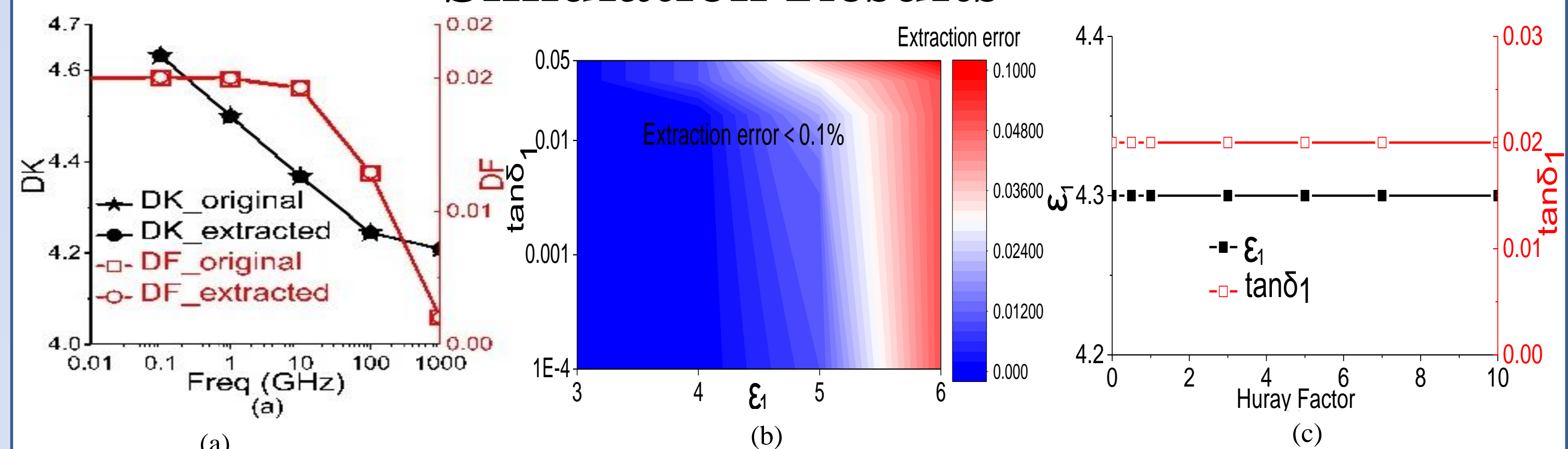
- The **on-striplines** method can extract DK and DF of a fabrication finished PCB not a raw dielectric substrate.

Proposed Method

Flow chart



Simulation Results



Results show the proposed method can accurately extract DK and DF on rough conductor in a broad frequency band.

Measurement Results

